

Cont A1

reference to the following description of an embodiment of the invention taken in conjunction with the accompanying drawings, wherein:

Page 6, line 4 please delete "B-O-B'" and replace it with --B-O-O'--.

Page 6, line 11 please delete "B-O-B'" and replace it with --B-O-O'--.

Page 6, line 26 please delete "C-O" and replace it with --B-O-B'--.

Page 7, line 3 please delete "(Description of Symbols)" and replace it with --DETAILED DESCRIPTION OF THE INVENTION--.

Page 8, line 23 after designates, please insert --a--.

Page 10, line 2 please change "pump" to --pumps--.

Page 10, line 3 please delete "as the following" and replace it with --as follows--.

Page 10, line 3 please insert --,-- after "First".

Page 10, line 21 please delete "an".

Page 11, line 6 please delete "them" and replace it with --three--.

Page 12, line 4 please insert --radiation is-- after "Microwave".

Page 12, line 5 please delete "is" and replace it with --and--.

Page 12, line 7 please delete "this micro wave creates" and replace it with --these microwaves create--.

Page 12, line 9 please delete "ashing" and replace it with --etching--.

Page 12, line 17 please insert --Reference number-- before "401".

Page 12, line 25 after "impress" please insert --a--.

Page 13, line 6 please delete "ashing" and replace it with --etching--.

IN THE CLAIMS

Please amend the following:

1. (Amended) A semiconductor manufacturing apparatus for processing a substrate surface, said apparatus comprising: [composed of]

a vacuum vessel having a plate and a substrate stage;
[wherein,]

at least one substrate stage is provided on said vacuum vessel [bottom] plate;

a cylinder is installed surrounding said substrate stage;

the gap between said cylinder and said vacuum vessel [top plate or bottom] plate is made variable by lifting/lowering said cylinder;